

AMENDMENTS TO THE CLAIMS:

Please cancel claim 3 without prejudice or disclaimer and amend the claims as follows:

1. (Currently Amended) A light emitting device, comprising:

a light emitting element; and

an adhesion layer to bond the light emitting element to a mounting ~~member, member;~~

wherein the adhesion layer is composed of inorganic material particles and a transparent inorganic binding layer to be formed between the neighboring inorganic material particles, and the inorganic material particles are substantially connected with each other in the adhesion ~~layer, and layer.~~

wherein the inorganic material particles are covered with the transparent inorganic binding layer, and the transparent inorganic binding layer has a thickness of equal to or less than an average diameter of the inorganic material particles.

2. (Original) The light emitting device according to claim 1, wherein:

the inorganic material particles are of diamond.

3. (Cancelled)

4. (Original) The light emitting device according to claim 1, wherein:

the light emitting element is of flip-chip type, and a space between an electrode face of the light emitting element and the mounting member is filled with the adhesion layer.

5. (Withdrawn) The light emitting device according to claim 1, wherein:

the transparent inorganic binding layer is formed by heating inorganic-coating forming liquid that includes a mixture of the hydrolysate and the hydrolysis/condensation polymer of an alkoxide compound represented by general formula: $M^{a+}(OR^1)_mR^{2}_{a-m}$, where

M includes any one of Si, Al, Zr and Ti, R¹ is hydrocarbon group with a carbon number of 1 to 5, alkoxyalkyl group or acyl group, R² is an organic group including at least one selected from vinyl, amino, imino, epoxy, acryloyloxy, methacryloyloxy, phenyl, mercapto and alkyl groups, a is a valance of M, and a and m are integers.

6. (Currently Amended) An adhesion layer for bonding a light emitting element to a member, comprising:

diamond particles; and

a transparent inorganic binding layer, layer;

wherein the diamond particles are covered with the transparent inorganic binding layer, and the transparent inorganic binding layer has a thickness of equal to or less than an average diameter of the diamond particles, and

wherein the diamond particles are substantially connected each other in the adhesion layer.

7. (Withdrawn) A method of forming an adhesion layer for bonding a light emitting element to a mounting member, comprising the steps of:

preparing adhesion layer precursor material by mixing inorganic-coating forming liquid and inorganic material particles; and

thermally treating the adhesion layer precursor material while laying the adhesion layer precursor material between the light emitting element and the mounting member.

8. (Withdrawn) The method according to claim 7, wherein:

the thermally treating step is conducted at a temperature of 500°C or lower.

9. (Withdrawn) The method according to claim 7, wherein:

the inorganic-coating forming liquid includes a mixture of the hydrolysate and the hydrolysis/condensation polymer of an alkoxide compound represented by general formula: $M^{a+}(OR^1)_mR^{2}_{a-m}$, where M includes any one of Si, Al, Zr and Ti, R^1 is hydrocarbon group with a carbon number of 1 to 5, alkoxyalkyl group or acyl group, R^2 is an organic group including at least one selected from vinyl, amino, imino, epoxy, acryloyloxy, methacryloyloxy, phenyl, mercapto and alkyl groups, a is a valance of M, and a and m are integers.

10. (Currently Amended) A light emitting device, comprising:

a light emitting element; and

an adhesion layer to bond the light emitting element to a mounting ~~member~~, ~~member~~;

wherein the adhesion layer is formed by thermally treating adhesion layer precursor material ~~that~~ in which inorganic-coating forming liquid and diamond particles are mixed,

the inorganic-coating forming liquid being a transparent inorganic binding layer, the diamond particles being covered with the transparent inorganic binding layer, and the transparent inorganic binding layer having a thickness of equal to or less than an average diameter of the diamond particles.

11.-36 (Withdrawn)